SUBMINIATURE SOLID STATE LAMP

AM27EC08

HIGH EFFICIENCY RED

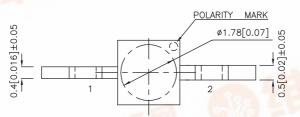
Features

- •SUBMINIATURE PACKAGE.
- •WIDE VIEWING ANGLE.
- •YOKE LEAD.
- •LONG LIFE-SOLID STATE RELIABILITY.
- •LOW PACKAGE PROFILE.
- •PACKAGE: 1000PCS / REEL.
- •RoHS COMPLIANT.

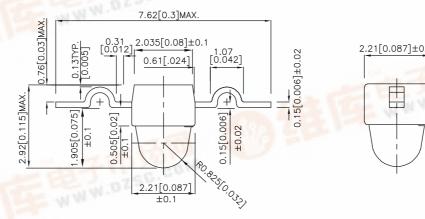
Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions







Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Lead spacing is measured where the lead emerge from the package.
- 4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Dice Lens Type Iv (mcd) @ 20 mA		,	Viewing Angle
			Min.	Тур.	2 θ 1/2
AM27EC08	HIGH EFFICIENCY RED (GaAsP/GaP)	WATER CLEAR	10	70	20°

Note

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD	Dominant Wavelength	High Efficiency Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF	Forward Voltage	High Efficiency Red	2.0	2.5	V	IF=20mA
lR	Reverse Current	High Efficiency Red		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

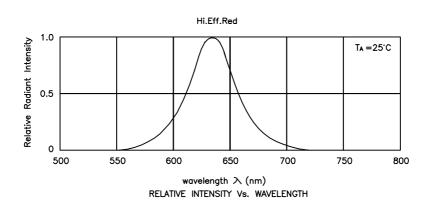
Parameter	High Efficiency Red	Units	
Power dissipation	105	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

Note

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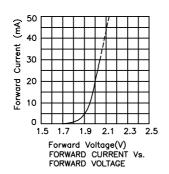
 $^{1. \}theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

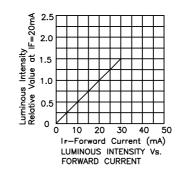
^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

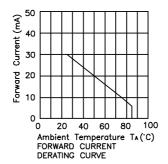


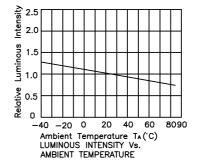
High Efficiency Red

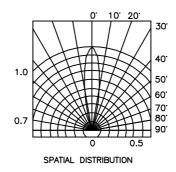
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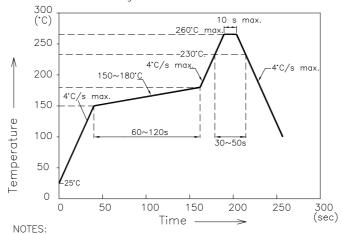




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Reflow Soldering Profile For Lead-free SMT Process.

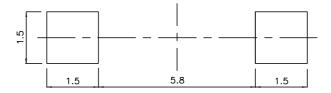


- NOTES:

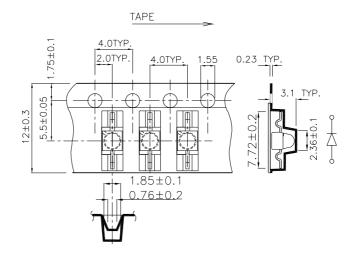
 1.We recommend the reflow temperature 245°C(±5°C). The maximum soldering temperature should be limited to 260°C.

 2. Don't cause stress to the energy resin while it is expose
 - 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:

- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2. Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

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